


Electronic Filing System (EFS) Data
Electronic Patent Application Submission
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Application ID: 10063131
Title of Invention: STI METHOD FOR SEMICONDUCTOR PROCESSES
First Named Inventor: Weng-Hsing Huang
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Total Fees Authorized: \$780.0
Payment Category: DA - Deposit Account
Deposit Account Number: 500801
Deposit Account Name: WINSTON HSU

TRANSMITTAL FORM



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Attorney Docket
Number:

MXIP0080USA

Submission Type: Utility
Patent Filing

STI METHOD FOR SEMICONDUCTOR PROCESSES

First Named Inventor: Weng-Hsing Huang

SUBMITTED BY

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Date Signed: 20020325

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Registration Number: 50,478

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Date Signed: 20020325

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I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.

Attached Files:

declaration	MXIP0080DEC1.TIF
declaration	MXIP0080DEC2.TIF
specification	MXIP0080.xml
bid-transmittal	MXIP0080apds.xml
patent-assignments	MXIP0080asgn.xml
fee-transmittal	MXIP0080fee.xml

Attached Image File(s):

MXIP0080DEC1.TIF
MXIP0080DEC2.TIF

MXIP0080DEC1.TIF
MXIP0080DEC2.TIF
MXIP0080.xml
MXIP0080apds.xml
MXIP0080asgn.xml
MXIP0080fee.xml

As a below named inventor , I hereby declare that :

"STI METHOD FOR SEMICONDUCTOR PROCESSES"

_____ The specification for the above entitled invention was filed previously

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of the invention disclosed in this application in accordance with Title 37, Code of Federal Regulations, Section 1.56 (a). I further acknowledge the duty in any continuation-in-part application to disclose to the Patent and Trademark Office all information known to be material to the patentability of the invention disclosed in this application, as defined in 1.56, which became available to me between the filing date of the prior application and the filing date of this application.

+ There is no claim of priority

Claim of priority is based on the following:

As a named inventor, I hereby appoint the following attorneys to prosecute this application and to transact all related business in the Patent and Trademark Office:

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DECLARATION

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued hereon.

Date: Dec. 20, 2001 Weng-Hsing Huang
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FEE TRANSMITTAL

Electronic Version 1.1.0

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Patent fees are subject to annual revisions on or about October 1st of each year.

Large Entity

TOTAL FEES AUTHORIZED: \$ 780

The commissioner is hereby authorized to charge indicated processing and/or publication fees and credit any overpayments to:

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Charge Any Additional Fee Required Under 37 C.F.R. Sections 1.16 and 1.17.

Charge Assignment Fees Required Under 37 C.F.R. Section 1.21 (h).

SUBMITTED BY

Authorized Name:

WINSTON HSU

Electronic Signature Mark:

VAEB-JMXX-8IIL

Date Signed:

20020325

BASIC FILING FEE

Fee Description	Fee Code	Fee Paid
Utility Filing Fee	101	\$ 740

Subtotal For Basic Filing Fee: \$ 740

EXTRA CLAIM FEES

	Fee Code	Fee	Extra Claims	Fee Paid
Total Claims: 7	103	\$ 18	0	\$ 0
Independent Claims: 1	102	\$ 84	0	\$ 0

Subtotal For Extra Claims Fees: \$ 0

ADDITIONAL FEES

Fee Description	Number	Quantity	Fee Code	Amount	Fee Paid
Recording Each Patent Assignment Per Property Fee	00000000	1	581	\$ 40	\$ 40

Subtotal For Additional Fees: \$ 40